

**Preliminary Amendment**

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Title: SEMICONDUCTOR DEVICE HAVING A CHIP STACK ON A REWIRING PLATE (as amended)

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**IN THE ABSTRACT**

Please replace the Abstract with the following rewritten paragraph:

**Abstract**

~~Semiconductor device having a semiconductor chip stack on a rewiring plate and production thereof~~

~~The invention relates to a~~ A semiconductor device (4) having a semiconductor chip stack (1) on a rewiring plate (2) is disclosed. In one embodiment, the device includes. ~~A~~an external contact area (5) having a plurality of external contact area regions (6,7) which are physically separate from one another is arranged on the underside (3). The individual external contact area regions (6,7) are assigned to the individual semiconductor chips (10,11) in the semiconductor chip stack. (1), ~~t~~The external contact regions (6,7) of an individual external contact area (5) ~~having~~ have a common external contact (14) which electrically connects the external contact area regions (6,7).

~~[Figure 1]~~